

## SN74LVC1G126 Single Bus Buffer Gate With 3-State Output

### 1 Features

- Available in the Texas Instruments NanoFree™ Package
- Supports 5-V  $V_{CC}$  Operation
- Inputs Accept Voltages to 5.5 V
- Provides Down Translation to  $V_{CC}$
- Max  $t_{pd}$  of 3.7 ns at 3.3 V
- Low Power Consumption, 10- $\mu$ A Max  $I_{CC}$
- $\pm 24$ -mA Output Drive at 3.3 V
- $I_{off}$  Supports Live Insertion, Partial-Power-Down Mode, and Back Drive Protection
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model
  - 200-V Machine Model
  - 1000-V Charged-Device Model

### 2 Applications

- Cable Modem Termination Systems
- High-Speed Data Acquisition and Generation
- Military: Radars and Sonars
- Motor Controls: High-Voltage
- Power Line Communication Modems
- SSDs: Internal or External
- Video Broadcasting and Infrastructure: Scalable Platforms
- Video Broadcasting: IP-Based Multi-Format Transcoders
- Video Communication Systems

### 3 Description

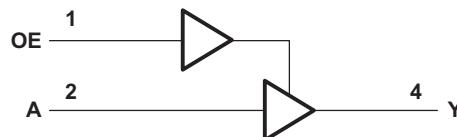
This single buffer is designed for 1.65-V to 3.6-V  $V_{CC}$  operation. The LVC1G126 device is a single line driver with 3-state output. The output is disabled when the output-enable input is low.

#### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE (PIN)	BODY SIZE
SN74LVC1G126	SOT-23 (5)	2.90 mm x 1.60 mm
	SC70 (5)	2.00 mm x 1.25 mm
	SOT (5)	1.60 mm x 1.20 mm
	SON (6)	1.00 mm x 1.00 mm
	XBGA (5)	1.40 mm x 0.90 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

### 4 Simplified Schematic



An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

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## 5 Revision History

### Changes from Revision Q (December 2013) to Revision R

	Page
• Added <i>Applications</i> , <i>Device Information</i> table, <i>Handling Ratings</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section.....	1

### Changes from Revision P (November 2012) to Revision Q

	Page
• Updated document to new TI data sheet format.....	1
• Changed MAX operating temperature to $125^\circ\text{C}$ in <i>Recommended Operating Conditions</i> table.....	5
• Added ESD warning.....	13

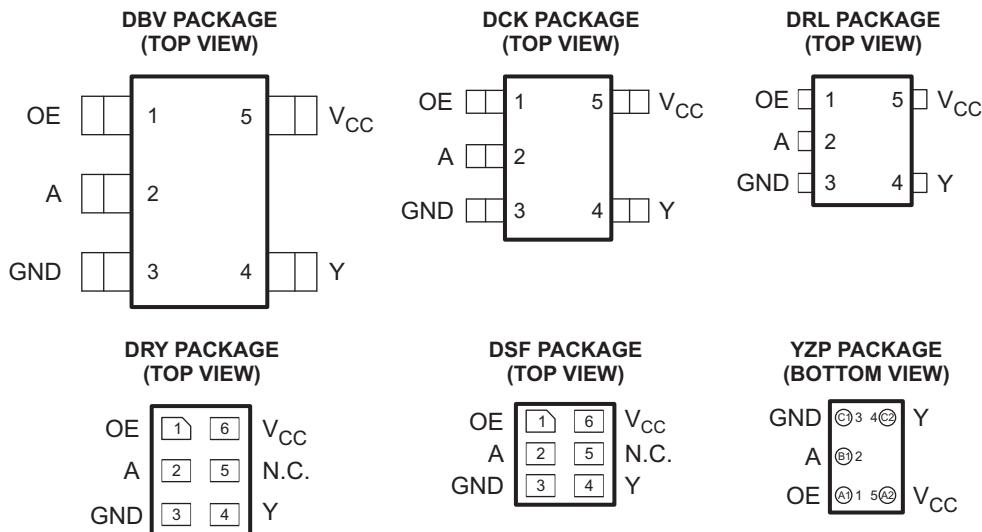
### Changes from Revision O (March 2011) to Revision P

	Page
• Removed Ordering Information table.....	1

### Changes from Revision N (February 2007) to Revision O

	Page
• Added DSF package option to the data sheet.....	3

## 6 Pin Configuration and Functions



See mechanical drawings for dimensions.

### Pin Functions

NAME	PIN		TYPE	DESCRIPTION		
	SN74LVC1G126					
	DBV, DCK, DRL, YZP	DRY, DSF				
A	2	2	I	A Input		
GND	3	3	—	Ground Pin		
NC	—	5	—	Do not connect		
OE	1	1	I	OE Enable/Input		
V <sub>CC</sub>	5	6	—	Power Pin		
Y	4	4	O	Y Output		

## 7 Specifications

### 7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	-0.5	6.5	V
$V_I$	Input voltage range <sup>(2)</sup>	-0.5	6.5	V
$V_O$	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	-0.5	6.5	V
$V_O$	Voltage range applied to any output in the high or low state <sup>(2)(3)</sup>	-0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Input clamp current	$V_I < 0$	-50	mA
$I_{OK}$	Output clamp current	$V_O < 0$	-50	mA
$I_O$	Continuous output current		$\pm 50$	mA
	Continuous current through $V_{CC}$ or GND		$\pm 100$	mA
$T_{stg}$	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of  $V_{CC}$  is provided in the *Recommended Operating Conditions* table.

### 7.2 ESD Ratings

PARAMETER	DEFINITION	VALUE	UNIT
$V_{(ESD)}$	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>	2000	V
	Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>	1000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	Operating	1.65	5.5	V
		Data retention only	1.5		
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>		V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.7		
		V <sub>CC</sub> = 3 V to 3.6 V	2		
		V <sub>CC</sub> = 4.5 V to 5.5 V	0.7 × V <sub>CC</sub>		
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.35 × V <sub>CC</sub>		V
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.7		
		V <sub>CC</sub> = 3 V to 3.6 V	0.8		
		V <sub>CC</sub> = 4.5 V to 5.5 V	0.3 × V <sub>CC</sub>		
V <sub>I</sub>	Input voltage		0	5.5	V
V <sub>O</sub>	Output voltage		0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 1.65 V	–4		mA
		V <sub>CC</sub> = 2.3 V	–8		
		V <sub>CC</sub> = 3 V	–16		
		V <sub>CC</sub> = 4.5 V	–24		
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 1.65 V	4		mA
		V <sub>CC</sub> = 2.3 V	8		
		V <sub>CC</sub> = 3 V	16		
		V <sub>CC</sub> = 4.5 V	24		
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V	20		ns/V
		V <sub>CC</sub> = 3.3 V ± 0.3 V	10		
		V <sub>CC</sub> = 5 V ± 0.5 V	5		
T <sub>A</sub>	Operating free-air temperature		–40	125	°C

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

### 7.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>	SN74LVC1G126					UNIT
	DBV	DCK	DRL	DRY	YZP	
	5 PINS	5 PINS	5 PINS	6 PINS	5 PINS	
R <sub>θJA</sub> Junction-to-ambient thermal resistance	206	252	142	234	132	°C/W

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

## 7.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	−40°C to 85°C			−40°C to 125°C			UNIT	
			MIN	TYP <sup>(1)</sup>	MAX	MIN	TYP <sup>(1)</sup>	MAX		
V <sub>OH</sub>	I <sub>OH</sub> = −100 µA	1.65 V to 5.5 V	V <sub>CC</sub> − 0.1			V <sub>CC</sub> − 0.1			V	
	I <sub>OH</sub> = −4 mA	1.65 V	1.2			1.2				
	I <sub>OH</sub> = −8 mA	2.3 V	1.9			1.9				
	I <sub>OH</sub> = −16 mA	3 V	2.4			2.4				
	I <sub>OH</sub> = −24 mA		2.3			2.3				
	I <sub>OH</sub> = −32 mA	4.5 V	3.8			3.8				
V <sub>OL</sub>	I <sub>OL</sub> = 100 µA	1.65 V to 5.5 V	0.1			0.1			V	
	I <sub>OL</sub> = 4 mA	1.65 V	0.45			0.45				
	I <sub>OL</sub> = 8 mA	2.3 V	0.3			0.3				
	I <sub>OL</sub> = 16 mA	3 V	0.4			0.4				
	I <sub>OL</sub> = 24 mA		0.55			0.55				
	I <sub>OL</sub> = 32 mA	4.5 V	0.55			0.55				
I <sub>I</sub>	A or OE inputs	V <sub>I</sub> = 5.5 V or GND	0 to 5.5 V			±5			µA	
I <sub>off</sub>		V <sub>I</sub> or V <sub>O</sub> = 5.5 V	0			±10			µA	
I <sub>OZ</sub>		V <sub>O</sub> = 0 to 5.5 V	3.6 V			10			µA	
I <sub>CC</sub>	V <sub>I</sub> = 5.5 V or GND	I <sub>O</sub> = 0	1.65 V to 5.5 V			10			µA	
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> − 0.6 V, Other inputs at V <sub>CC</sub> or GND		3 V to 5.5 V			500			µA	
C <sub>I</sub>		V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V			4			pF	

(1) All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

## 7.6 Switching Characteristics, C<sub>L</sub> = 15 pF

over recommended operating free-air temperature range, C<sub>L</sub> = 15 pF (unless otherwise noted) (see [Figure 3](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	−40°C to 85°C								UNIT	
			V <sub>CC</sub> = 1.8 V ± 0.15 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 5 V ± 0.5 V			
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
t <sub>pd</sub>	A	Y	1.7	6.9	0.6	4.6	0.6	3.7	0.5	3.4	ns	

## 7.7 Switching Characteristics, −40°C to 85°C

over recommended operating free-air temperature range, C<sub>L</sub> = 30 pF or 50 pF (unless otherwise noted) (see [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	−40°C to 85°C								UNIT	
			V <sub>CC</sub> = 1.8 V ± 0.15 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 5 V ± 0.5 V			
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
t <sub>pd</sub>	A	Y	2.6	8	1.1	5.5	1	4.5	1	4	ns	
t <sub>en</sub>	OE	Y	2.8	9.4	1.3	6.6	1.2	5.3	1	5	ns	
t <sub>dis</sub>	OE	Y	1.6	9.8	1	5.5	1	5.5	1	4.2	ns	

## 7.8 Switching Characteristics, $-40^{\circ}\text{C}$ to $125^{\circ}\text{C}$

over recommended operating free-air temperature range,  $C_L = 30 \text{ pF}$  or  $50 \text{ pF}$  (unless otherwise noted) (see [Figure 4](#))

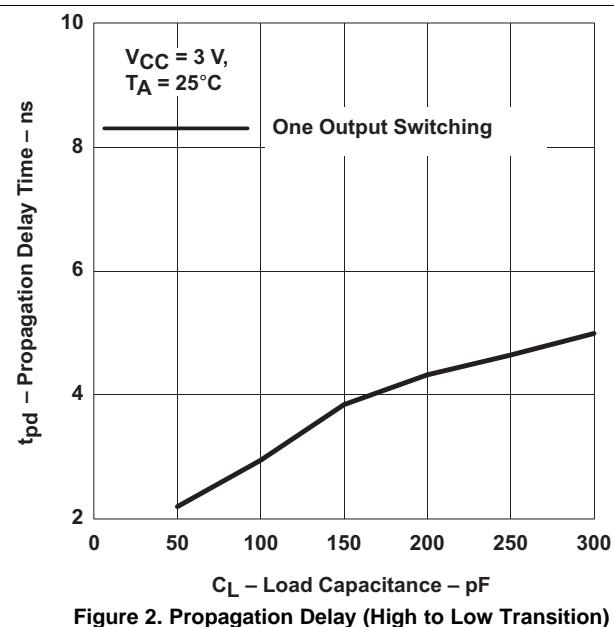
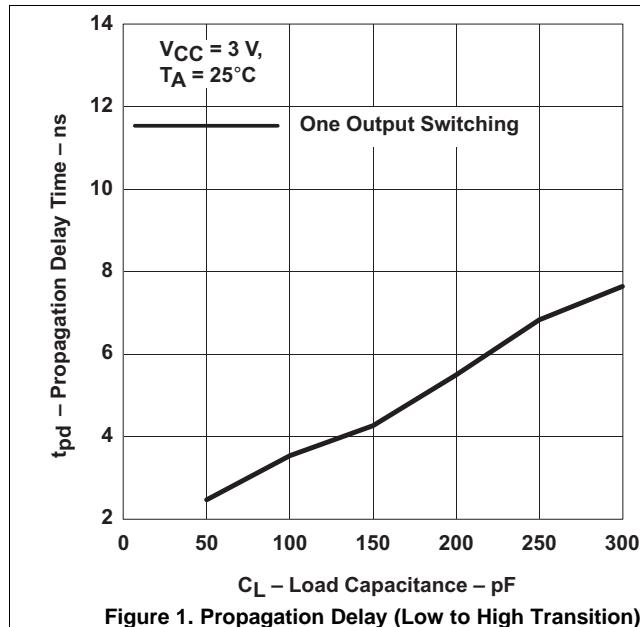
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$-40^{\circ}\text{C}$ to $125^{\circ}\text{C}$						UNIT	
			$V_{CC} = 1.8 \text{ V}$ $\pm 0.15 \text{ V}$		$V_{CC} = 2.5 \text{ V}$ $\pm 0.2 \text{ V}$		$V_{CC} = 3.3 \text{ V}$ $\pm 0.3 \text{ V}$		$V_{CC} = 5 \text{ V}$ $\pm 0.5 \text{ V}$	
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX
$t_{pd}$	A	Y	2.6	9	1.1	5.7	1	4.7	1	4.2
$t_{en}$	OE	Y	2.8	9.6	1.3	6.8	1.2	5.5	1	5.2
$t_{dis}$	OE	Y	1.6	10	1	5.7	1	5.7	1	4.4

## 7.9 Operating Characteristics

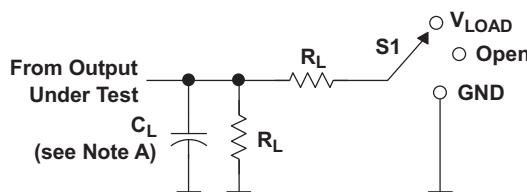
$T_A = 25^{\circ}\text{C}$

PARAMETER	TEST CONDITIONS	$V_{CC} = 1.8 \text{ V}$	$V_{CC} = 2.5 \text{ V}$	$V_{CC} = 3.3 \text{ V}$	$V_{CC} = 5 \text{ V}$	UNIT
		TYP	TYP	TYP	TYP	
	$f = 10 \text{ MHz}$					
$C_{pd}$ Power dissipation capacitance	Outputs enabled	19	19	19	21	pF
	Outputs disabled	2	2	3	4	

## 7.10 Typical Characteristics



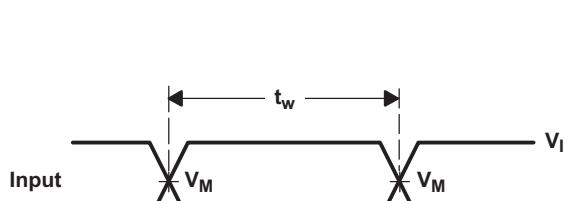
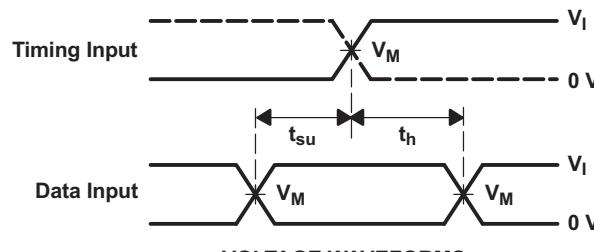
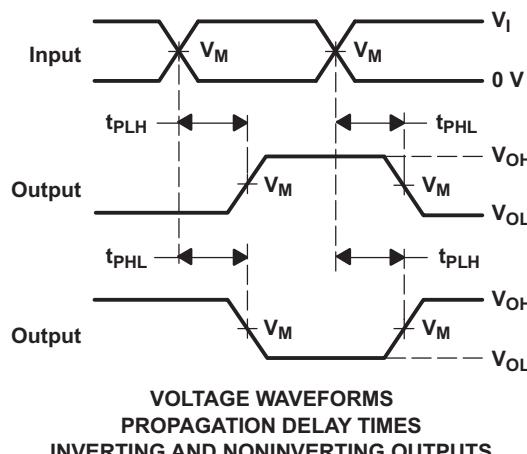
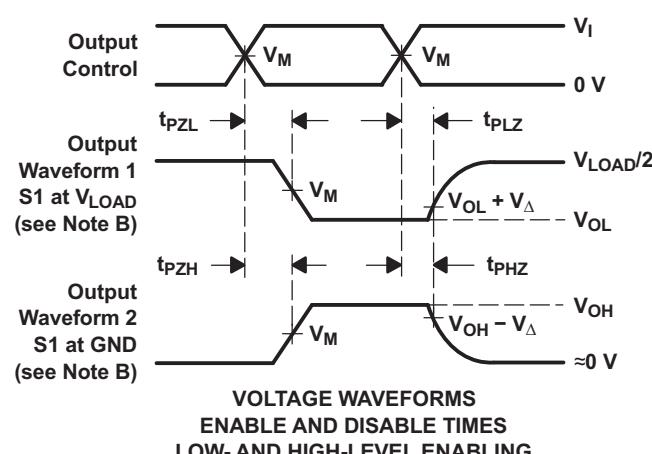
## 8 Parameter Measurement Information



TEST	$S_1$
$t_{PLH}/t_{PHL}$	Open
$t_{PZL}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

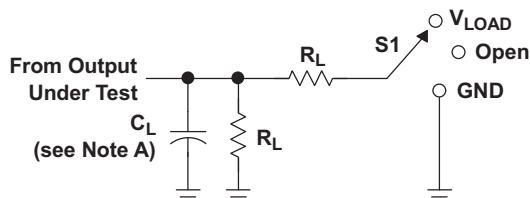
LOAD CIRCUIT

$V_{CC}$	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_\Delta$
	$V_I$	$t_r/t_f$					
$1.8\text{ V} \pm 0.15\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	1 M $\Omega$	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	1 M $\Omega$	0.15 V
$3.3\text{ V} \pm 0.3\text{ V}$	3 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	15 pF	1 M $\Omega$	0.3 V
$5\text{ V} \pm 0.5\text{ V}$	$V_{CC}$	$\leq 2.5\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	1 M $\Omega$	0.3 V

VOLTAGE WAVEFORMS  
PULSE DURATIONVOLTAGE WAVEFORMS  
SETUP AND HOLD TIMESVOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTSVOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING

NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq 10\text{ MHz}$ ,  $Z_O = 50\text{ }\Omega$ .  
 D. The outputs are measured one at a time, with one transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .  
 H. All parameters and waveforms are not applicable to all devices.

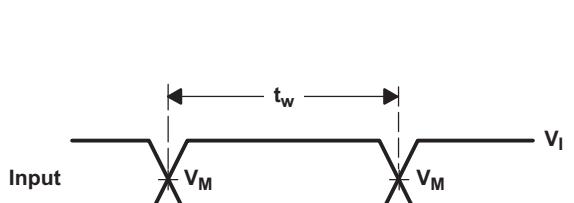
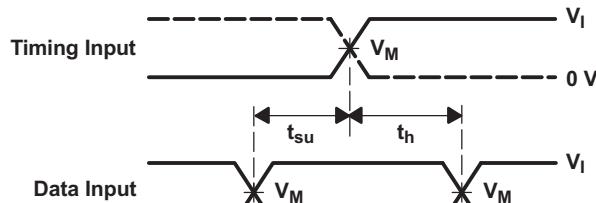
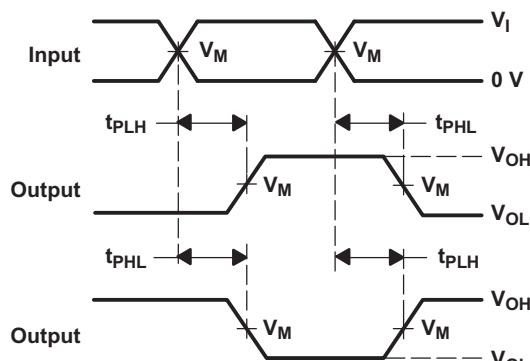
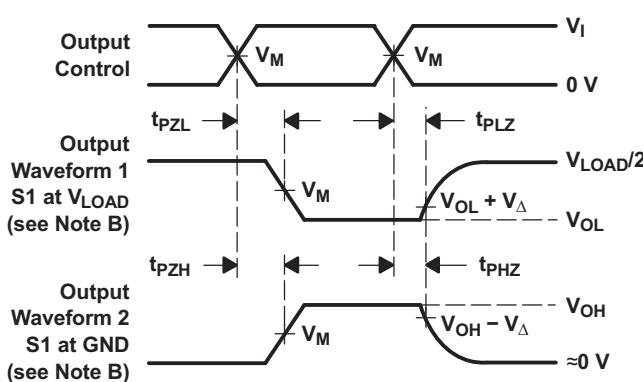
Figure 3. Load Circuit and Voltage Waveforms

**Parameter Measurement Information (continued)**


TEST	$S_1$
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

**LOAD CIRCUIT**

$V_{CC}$	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_\Delta$
	$V_I$	$t_r/t_f$					
$1.8 \text{ V} \pm 0.15 \text{ V}$	$V_{CC}$	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k $\Omega$	0.15 V
$2.5 \text{ V} \pm 0.2 \text{ V}$	$V_{CC}$	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 $\Omega$	0.15 V
$3.3 \text{ V} \pm 0.3 \text{ V}$	3 V	$\leq 2.5 \text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
$5 \text{ V} \pm 0.5 \text{ V}$	$V_{CC}$	$\leq 2.5 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	50 pF	500 $\Omega$	0.3 V


**VOLTAGE WAVEFORMS  
PULSE DURATION**

**VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES**

**VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTS**

**VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING**

NOTES: A.  $C_L$  includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ .

D. The outputs are measured one at a time, with one transition per measurement.

E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .

F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .

G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

H. All parameters and waveforms are not applicable to all devices.

**Figure 4. Load Circuit and Voltage Waveforms**

## 9 Detailed Description

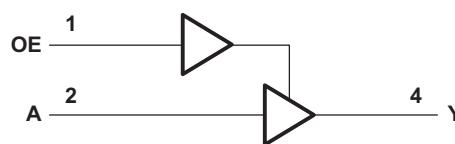
### 9.1 Overview

The SN74LVC1G126 device contains a dual buffer gate with output enable control and performs the Boolean function  $Y = A$ .

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pull-down resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

### 9.2 Functional Block Diagram



### 9.3 Feature Description

- 1.65 V to 5.5 V operating voltage range
- Allows down voltage translation
  - 5 V to 3.3 V
  - 5 V or 3.3 V to 1.8 V
- Inputs accept voltages to 5.5 V
  - 5.5-V tolerance on input pin when  $V_{CC} = 0$  V
- $I_{off}$  feature
  - Allows voltage on the inputs and outputs when  $V_{CC}$  is 0 V
  - Able to reduce leakage when  $V_{CC}$  is 0 V

### 9.4 Device Functional Modes

**Table 1. Function Table**

INPUTS		OUTPUT Y
OE	A	
H	H	H
H	L	L
L	X	Z

## 10 Application and Implementation

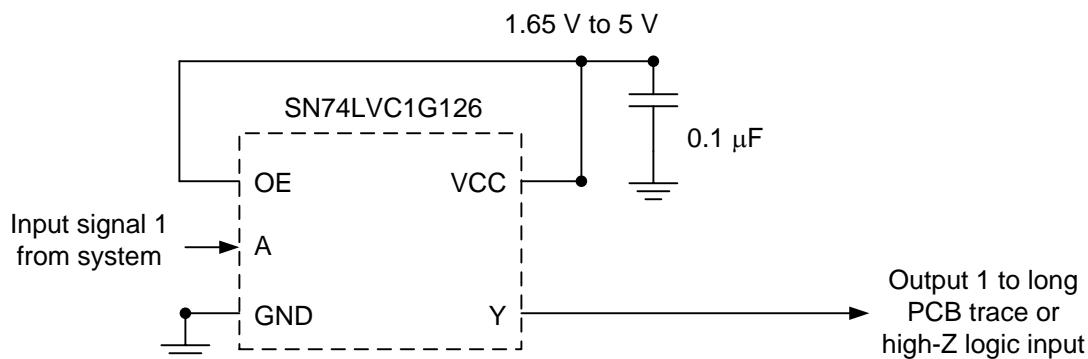
### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 10.1 Application Information

The SN74LVC1G126 device is a high-drive CMOS device that can be used as an output enabled buffer with a high output drive, such as an LED application. It can produce 24 mA of drive current at 3.3 V, making it ideal for driving multiple outputs and good for high speed applications up to 100 MHz. The inputs are 5.5-V tolerant allowing it to translate down to  $V_{CC}$ .

### 10.2 Typical Application



**Figure 5. Application Schematic**

#### 10.2.1 Design Requirements

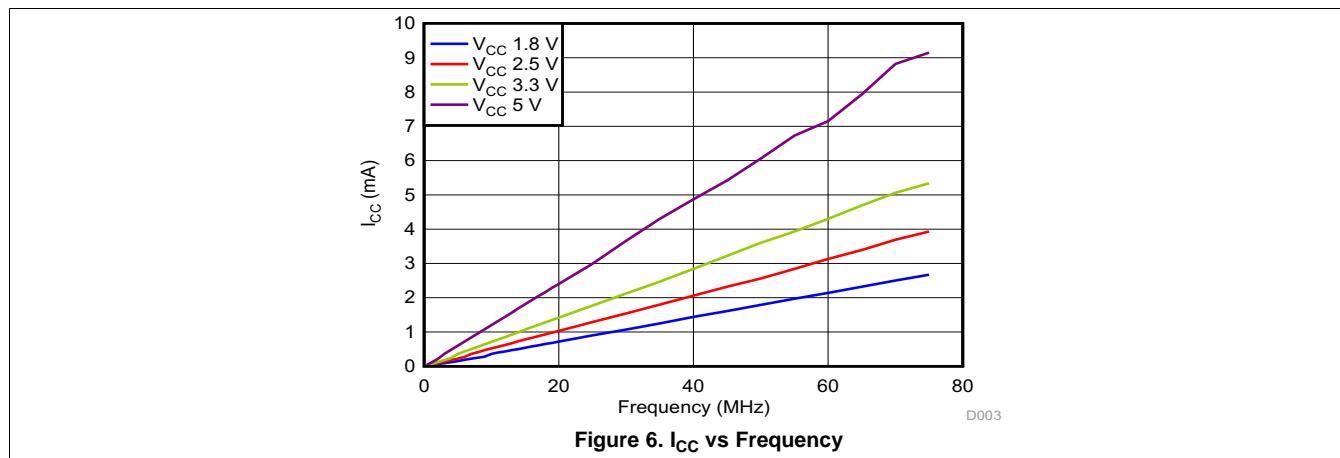
This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. Outputs can be combined to produce higher drive but the high drive will also create faster edges into light loads, so routing and load conditions should be considered to prevent ringing.

#### 10.2.2 Detailed Design Procedure

1. Recommended Input Conditions:
  - For rise time and fall time specifications, see  $\Delta t/\Delta V$  in the [Recommended Operating Conditions](#) table.
  - For specified high and low levels, see  $V_{IH}$  and  $V_{IL}$  in the [Recommended Operating Conditions](#) table.
  - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid  $V_{CC}$ .
2. Recommend Output Conditions:
  - Load currents should not exceed 50 mA per output and 100 mA total for the part.

## Typical Application (continued)

### 10.2.3 Application Curves



## 11 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the *Recommended Operating Conditions* table.

Each  $V_{CC}$  terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, a 0.1- $\mu\text{F}$  capacitor is recommended. If there are multiple  $V_{CC}$  terminals, then 0.01- $\mu\text{F}$  or 0.022- $\mu\text{F}$  capacitors are recommended for each power terminal. It is ok to parallel multiple bypass capacitors to reject different frequencies of noise. Multiple bypass capacitors may be paralleled to reject different frequencies of noise. The bypass capacitor should be installed as close to the power terminal as possible for the best results.

## 12 Layout

### 12.1 Layout Guidelines

When using multiple bit logic devices, inputs should not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input AND gate are used, or when only 3 of the 4-buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states.

Specified in [Figure 7](#) are rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or  $V_{CC}$ , whichever makes more sense or is more convenient. It is acceptable to float outputs unless the part is a transceiver. If the transceiver has an output enable pin, it will disable the outputs section of the part when asserted. This will not disable the input section of the I/Os so they also cannot float when disabled.

### 12.2 Layout Example

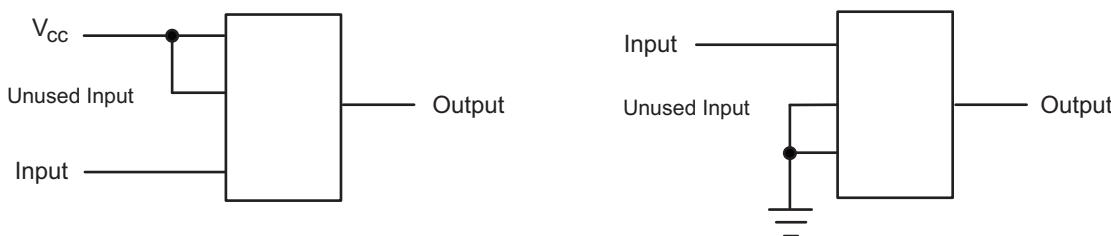


Figure 7. Layout Diagram

## 13 Device and Documentation Support

### 13.1 Trademarks

NanoFree is a trademark of Texas Instruments.  
All other trademarks are the property of their respective owners.

### 13.2 Electrostatic Discharge Caution

 These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 13.3 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms and definitions.

## 14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
74LVC1G126DBVRE4	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C26F
<b>74LVC1G126DBVRG4</b>	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C26F
74LVC1G126DBVRG4.A	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C26F
74LVC1G126DBVRG4.B	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C26F
74LVC1G126DBVTE4	Active	Production	SOT-23 (DBV)   5	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C26F
<b>74LVC1G126DBVTG4</b>	Active	Production	SOT-23 (DBV)   5	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C26F
74LVC1G126DBVTG4.B	Active	Production	SOT-23 (DBV)   5	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C26F
74LVC1G126DCKRE4	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CN5
<b>74LVC1G126DCKRG4</b>	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CN5
74LVC1G126DCKRG4.A	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CN5
74LVC1G126DCKRG4.B	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CN5
<b>74LVC1G126DCKTG4</b>	Active	Production	SC70 (DCK)   5	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CN5
74LVC1G126DCKTG4.B	Active	Production	SC70 (DCK)   5	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CN5
<b>SN74LVC1G126DBVR</b>	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	(C265, C26F, C26J, C26K, C26R, C26T)
SN74LVC1G126DBVR.A	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(C265, C26F, C26J, C26K, C26R, C26T)
SN74LVC1G126DBVR.B	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(C265, C26F, C26J, C26K, C26R, C26T)
SN74LVC1G126DBVRG4	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C26J
SN74LVC1G126DBVRG4.A	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C26J
SN74LVC1G126DBVRG4.B	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C26J
<b>SN74LVC1G126DBVT</b>	Active	Production	SOT-23 (DBV)   5	250   SMALL T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	(C265, C26F, C26J, C26K, C26R)
SN74LVC1G126DBVT.B	Active	Production	SOT-23 (DBV)   5	250   SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	(C265, C26F, C26J, C26K, C26R)
<b>SN74LVC1G126DCKR</b>	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	(CN5, CNF, CNJ, CNK, CNR, CNT)

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74LVC1G126DCKR.A	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	(CN5, CNF, CNJ, CNK, CNR, CNT)
SN74LVC1G126DCKR.B	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	(CN5, CNF, CNJ, CNK, CNR, CNT)
<b>SN74LVC1G126DCKT</b>	Active	Production	SC70 (DCK)   5	250   SMALL T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	(CN5, CNF, CNJ, CNK, CNR)
SN74LVC1G126DCKT.B	Active	Production	SC70 (DCK)   5	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(CN5, CNF, CNJ, CNK, CNR)
SN74LVC1G126DCKTG4.B	Active	Production	SC70 (DCK)   5	250   SMALL T&R	-	Call TI	Call TI	-40 to 125	
<b>SN74LVC1G126DRLR</b>	Active	Production	SOT-5X3 (DRL)   5	4000   LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	(CN7, CNR)
SN74LVC1G126DRLR.A	Active	Production	SOT-5X3 (DRL)   5	4000   LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	(CN7, CNR)
SN74LVC1G126DRLR.B	Active	Production	SOT-5X3 (DRL)   5	4000   LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	(CN7, CNR)
<b>SN74LVC1G126DRYR</b>	Active	Production	SON (DRY)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CN
SN74LVC1G126DRYR.B	Active	Production	SON (DRY)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CN
SN74LVC1G126DRYRG4.B	Active	Production	SON (DRY)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CN
<b>SN74LVC1G126DSFR</b>	Active	Production	SON (DSF)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CN
SN74LVC1G126DSFR.B	Active	Production	SON (DSF)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CN
SN74LVC1G126DSFRG4	Active	Production	SON (DSF)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CN
SN74LVC1G126DSFRG4.B	Active	Production	SON (DSF)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CN
<b>SN74LVC1G126YZPR</b>	Active	Production	DSBGA (YZP)   5	3000   LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	(CN7, CNN)
SN74LVC1G126YZPR.B	Active	Production	DSBGA (YZP)   5	3000   LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	(CN7, CNN)

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

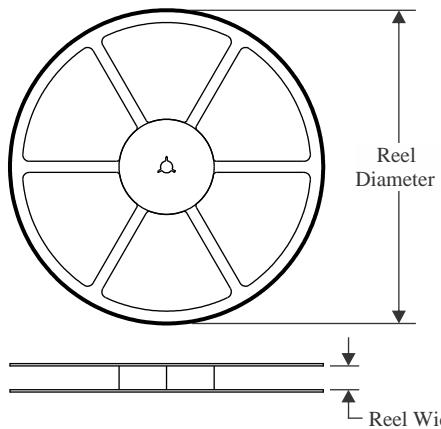
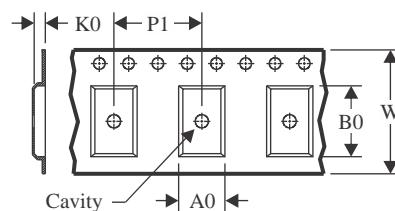
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN74LVC1G126 :**

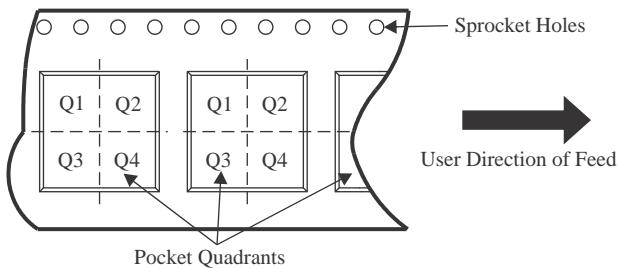
- Automotive : [SN74LVC1G126-Q1](#)
- Enhanced Product : [SN74LVC1G126-EP](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


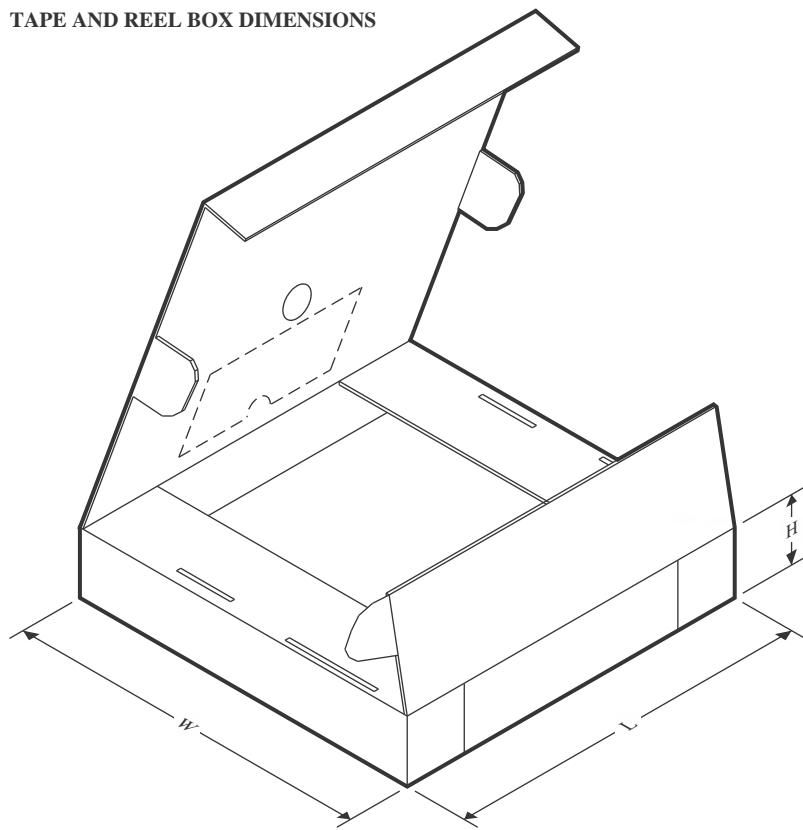
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74LVC1G126DBVRG4	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
74LVC1G126DBVTG4	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
74LVC1G126DCKRG4	SC70	DCK	5	3000	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
74LVC1G126DCKTG4	SC70	DCK	5	250	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
SN74LVC1G126DBVR	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
SN74LVC1G126DBVRG4	SOT-23	DBV	5	3000	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
SN74LVC1G126DBVT	SOT-23	DBV	5	250	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
SN74LVC1G126DBVT	SOT-23	DBV	5	250	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
SN74LVC1G126DCKR	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74LVC1G126DCKR	SC70	DCK	5	3000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
SN74LVC1G126DCKR	SC70	DCK	5	3000	180.0	8.4	2.3	2.5	1.2	4.0	8.0	Q3
SN74LVC1G126DCKT	SC70	DCK	5	250	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3
SN74LVC1G126DCKT	SC70	DCK	5	250	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74LVC1G126DCKT	SC70	DCK	5	250	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
SN74LVC1G126DRLR	SOT-5X3	DRL	5	4000	180.0	8.4	1.98	1.78	0.69	4.0	8.0	Q3
SN74LVC1G126DRYR	SON	DRY	6	5000	180.0	9.5	1.2	1.65	0.7	4.0	8.0	Q1

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC1G126DSFR	SON	DSF	6	5000	180.0	9.5	1.16	1.16	0.5	4.0	8.0	Q2
SN74LVC1G126DSFRG4	SON	DSF	6	5000	180.0	9.5	1.16	1.16	0.5	4.0	8.0	Q2
SN74LVC1G126YZPR	DSBGA	YZP	5	3000	178.0	9.2	1.02	1.52	0.63	4.0	8.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74LVC1G126DBVRG4	SOT-23	DBV	5	3000	180.0	180.0	18.0
74LVC1G126DBVTG4	SOT-23	DBV	5	250	180.0	180.0	18.0
74LVC1G126DCKRG4	SC70	DCK	5	3000	180.0	180.0	18.0
74LVC1G126DCKTG4	SC70	DCK	5	250	180.0	180.0	18.0
SN74LVC1G126DBVR	SOT-23	DBV	5	3000	208.0	191.0	35.0
SN74LVC1G126DBVRG4	SOT-23	DBV	5	3000	210.0	185.0	35.0
SN74LVC1G126DBVT	SOT-23	DBV	5	250	210.0	185.0	35.0
SN74LVC1G126DBVT	SOT-23	DBV	5	250	210.0	185.0	35.0
SN74LVC1G126DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
SN74LVC1G126DCKR	SC70	DCK	5	3000	208.0	191.0	35.0
SN74LVC1G126DCKR	SC70	DCK	5	3000	210.0	185.0	35.0
SN74LVC1G126DCKT	SC70	DCK	5	250	202.0	201.0	28.0
SN74LVC1G126DCKT	SC70	DCK	5	250	180.0	180.0	18.0
SN74LVC1G126DCKT	SC70	DCK	5	250	180.0	180.0	18.0
SN74LVC1G126DRLR	SOT-5X3	DRL	5	4000	202.0	201.0	28.0
SN74LVC1G126DRYR	SON	DRY	6	5000	189.0	185.0	36.0
SN74LVC1G126DSFR	SON	DSF	6	5000	184.0	184.0	19.0
SN74LVC1G126DSFRG4	SON	DSF	6	5000	184.0	184.0	19.0

---

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC1G126YZPR	DSBGA	YZP	5	3000	220.0	220.0	35.0

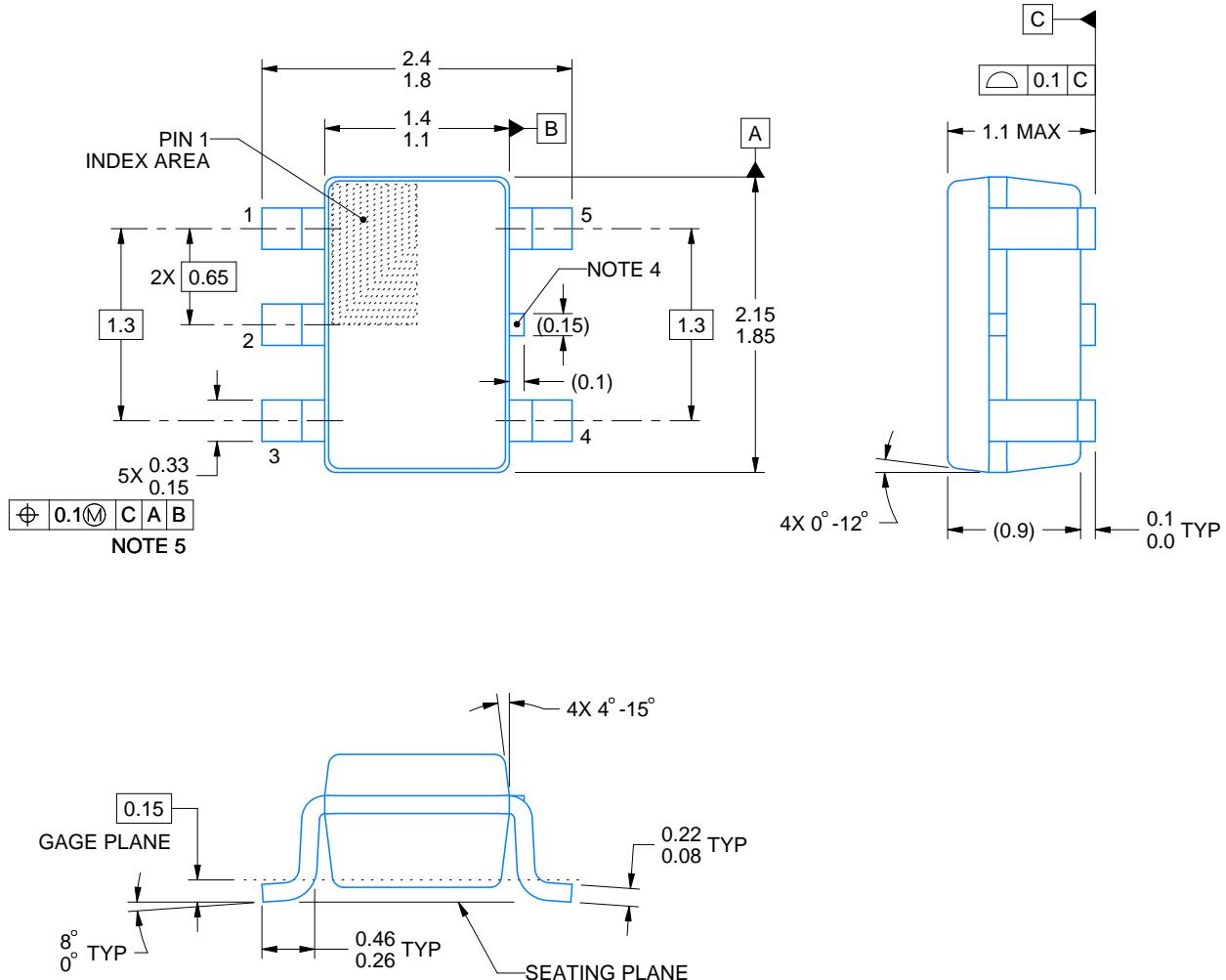
## PACKAGE OUTLINE

**DCK0005A**



## SOT - 1.1 max height

## SMALL OUTLINE TRANSISTOR



4214834/G 11/2024

## NOTES:

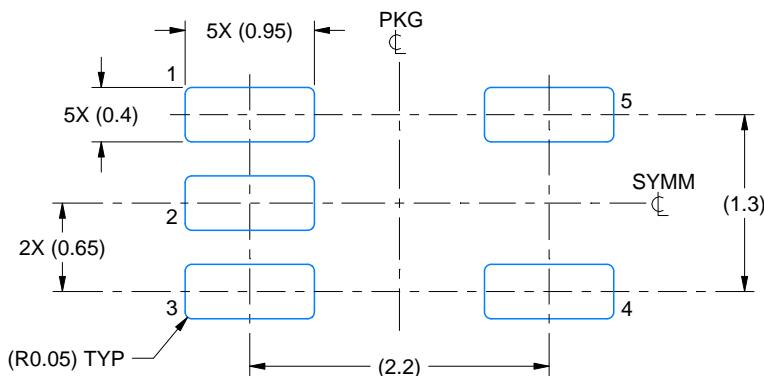
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-203.
4. Support pin may differ or may not be present.
5. Lead width does not comply with JEDEC.
6. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side

# EXAMPLE BOARD LAYOUT

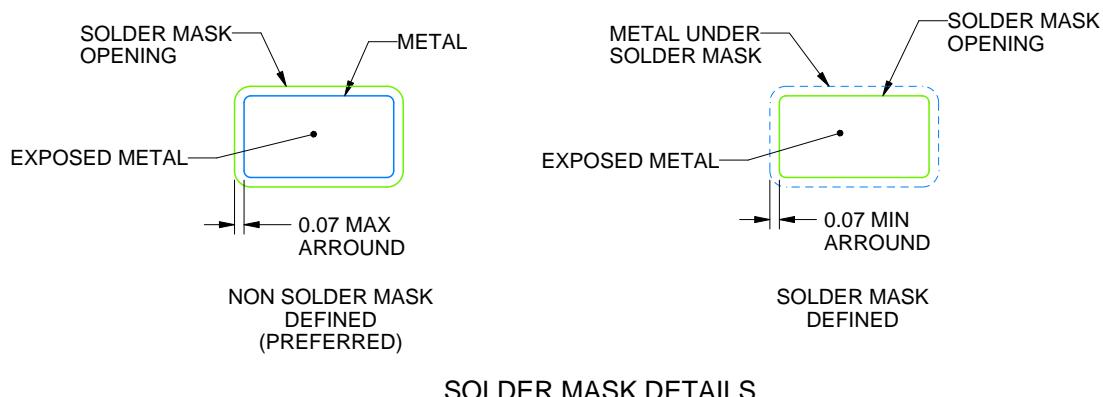
DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:18X



4214834/G 11/2024

NOTES: (continued)

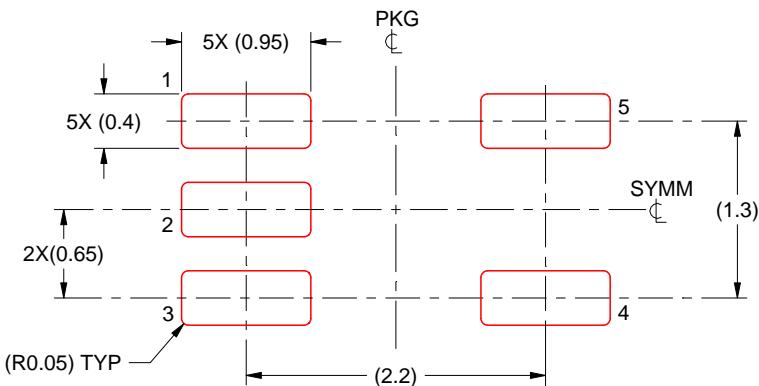
7. Publication IPC-7351 may have alternate designs.
8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 THICK STENCIL  
SCALE:18X

4214834/G 11/2024

NOTES: (continued)

9. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
10. Board assembly site may have different recommendations for stencil design.

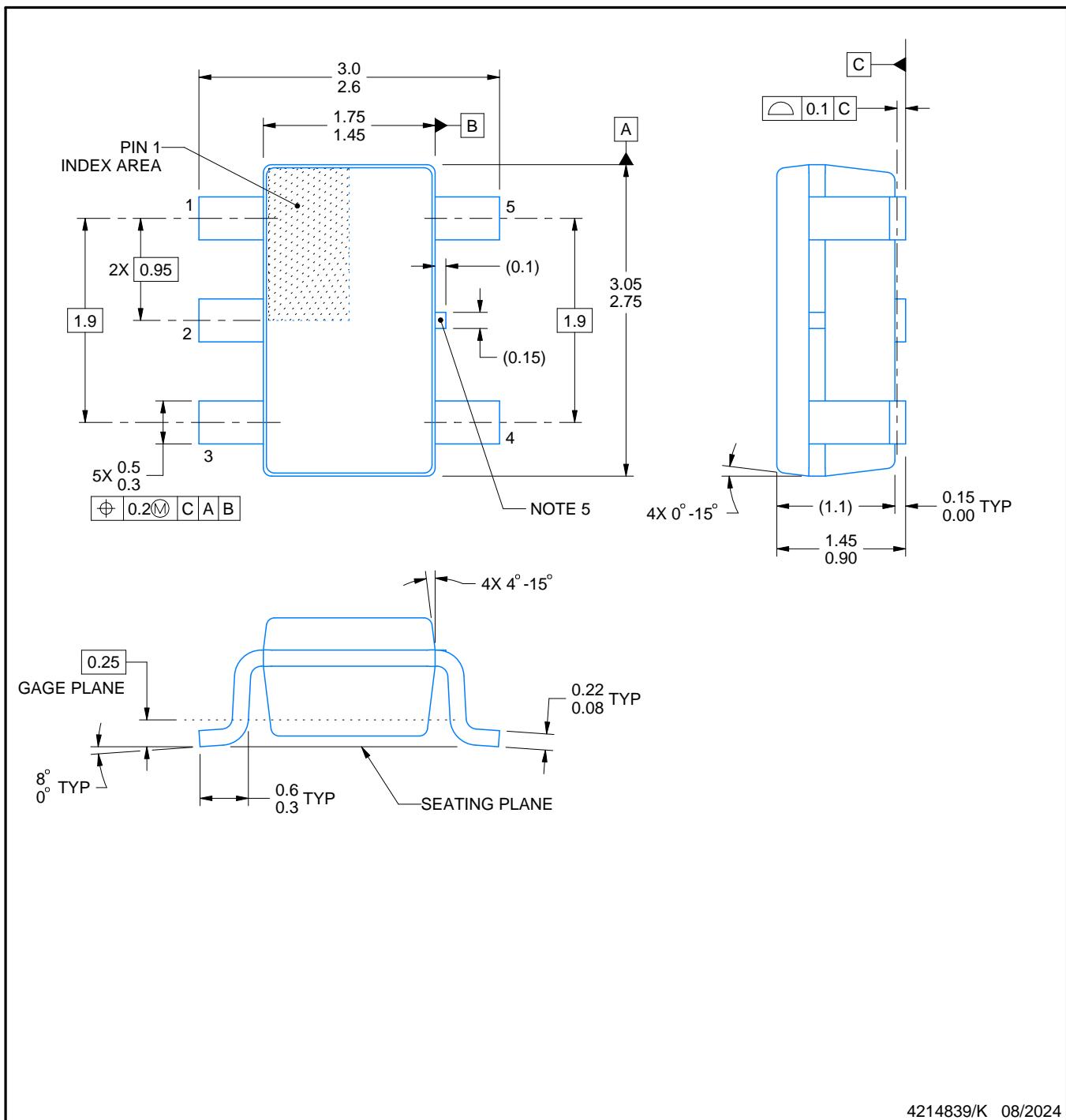
# PACKAGE OUTLINE

DBV0005A



SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



NOTES:

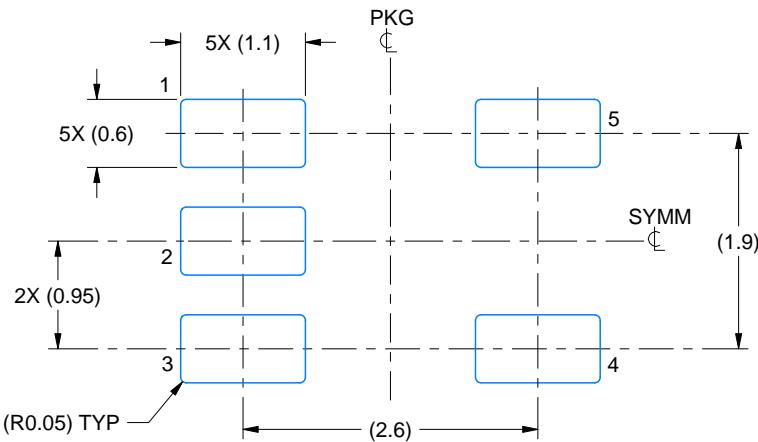
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- Reference JEDEC MO-178.
- Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
- Support pin may differ or may not be present.

# EXAMPLE BOARD LAYOUT

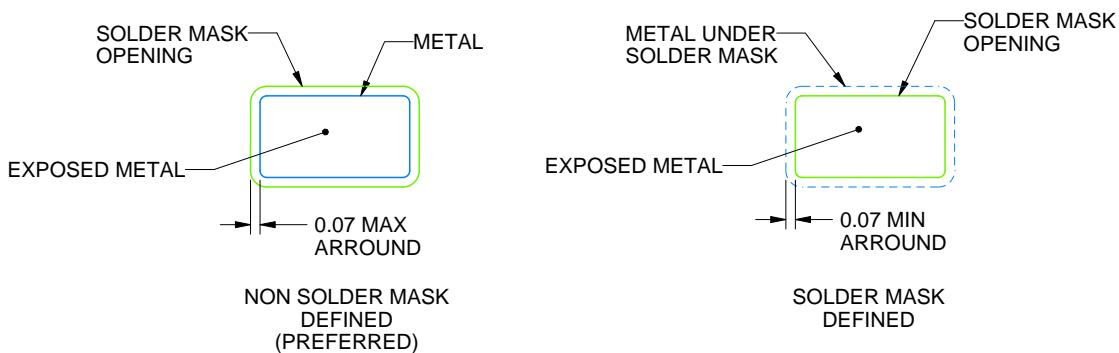
DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:15X



SOLDER MASK DETAILS

4214839/K 08/2024

NOTES: (continued)

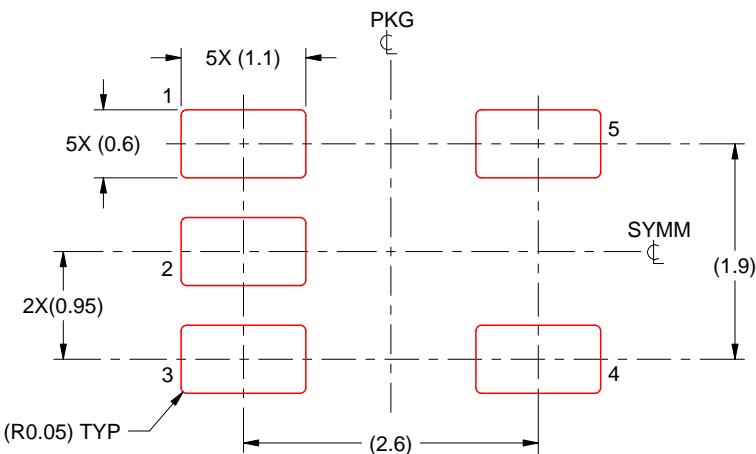
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:15X

4214839/K 08/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

DRY 6

## GENERIC PACKAGE VIEW

### USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD

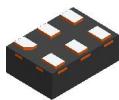


Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4207181/G

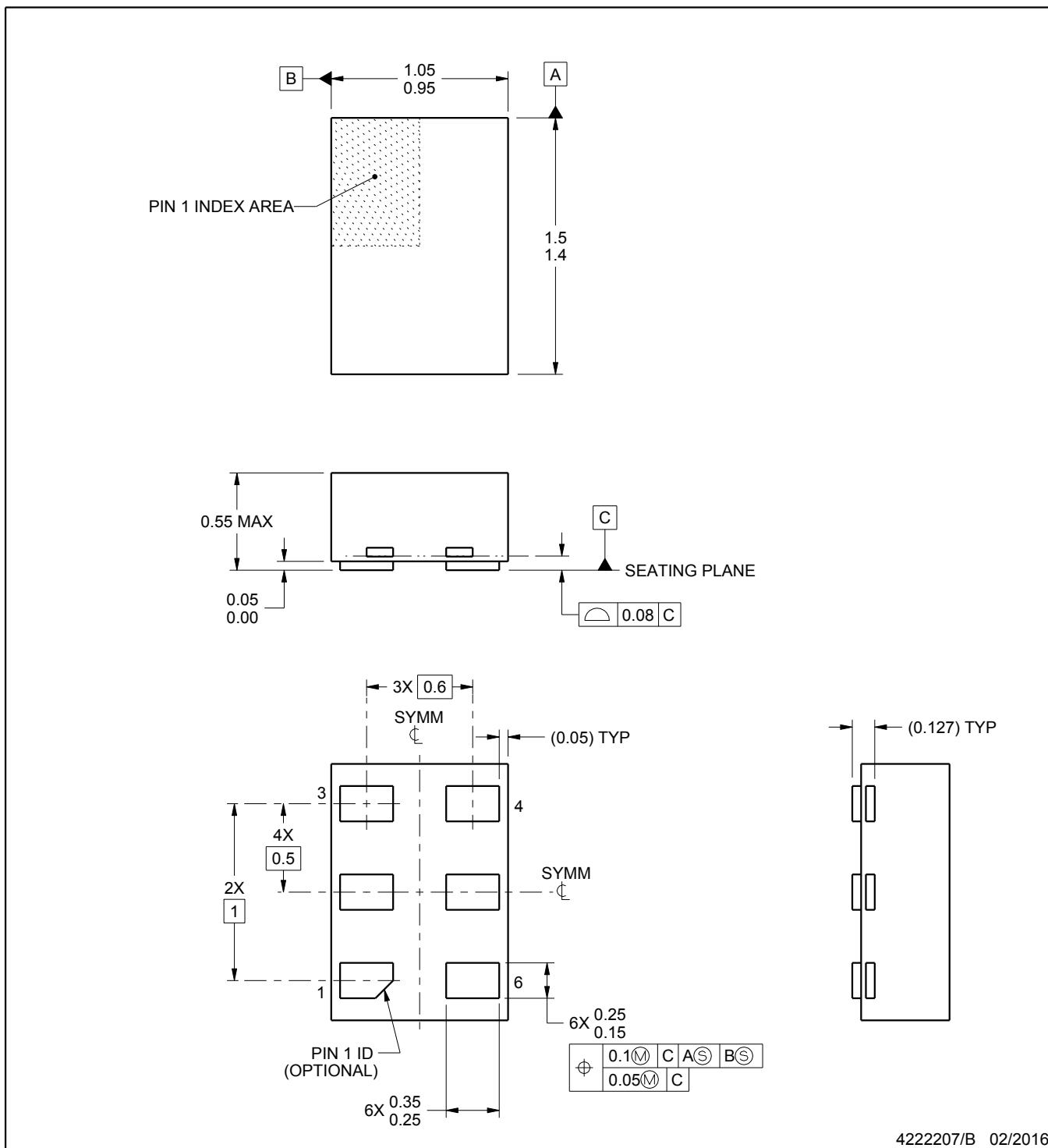
# PACKAGE OUTLINE

DRY0006B



USON - 0.55 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



4222207/B 02/2016

## NOTES:

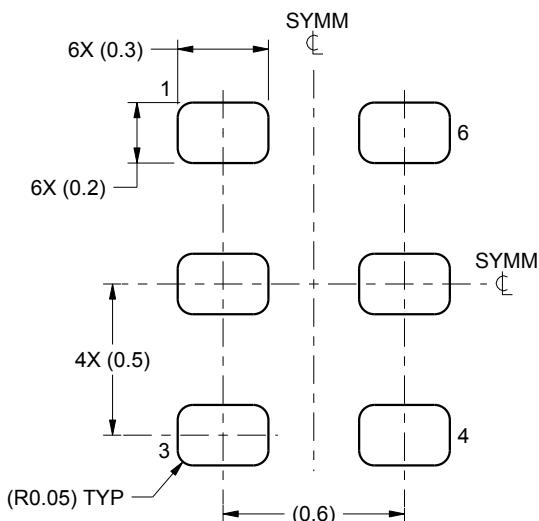
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

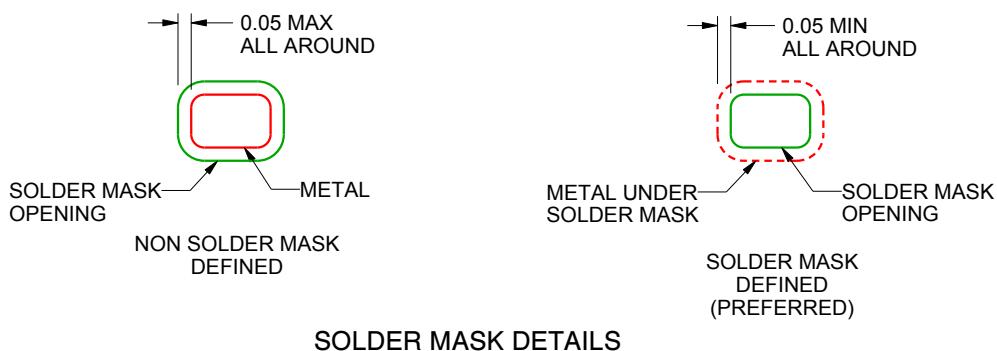
DRY0006B

USON - 0.55 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE  
1:1 RATIO WITH PKG SOLDER PADS  
SCALE:40X



4222207/B 02/2016

NOTES: (continued)

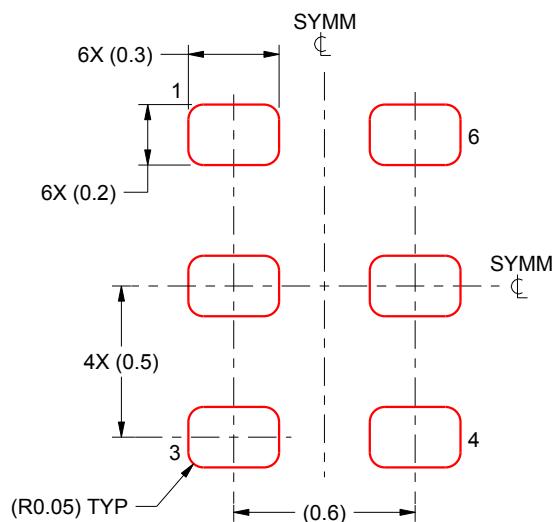
3. For more information, see QFN/SON PCB application report in literature No. SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).

## EXAMPLE STENCIL DESIGN

**DRY0006B**

## **USON - 0.55 mm max height**

## PLASTIC SMALL OUTLINE - NO LEAD



**SOLDER PASTE EXAMPLE  
BASED ON 0.075 - 0.1 mm THICK STENCIL  
SCALE:40X**

4222207/B 02/2016

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

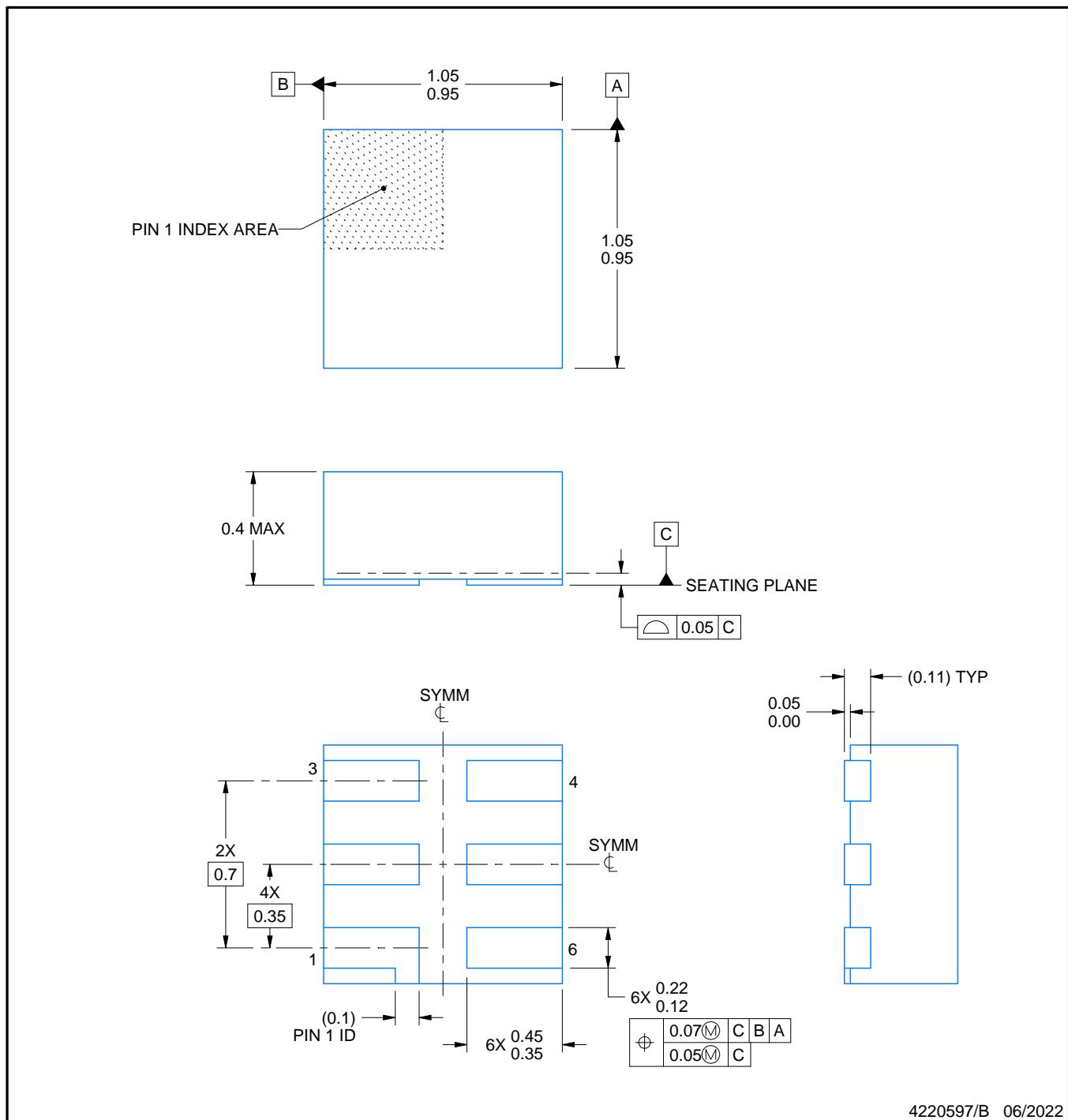


## PACKAGE OUTLINE

**DSF0006A**

## X2SON - 0.4 mm max height

## PLASTIC SMALL OUTLINE - NO LEAD



## NOTES:

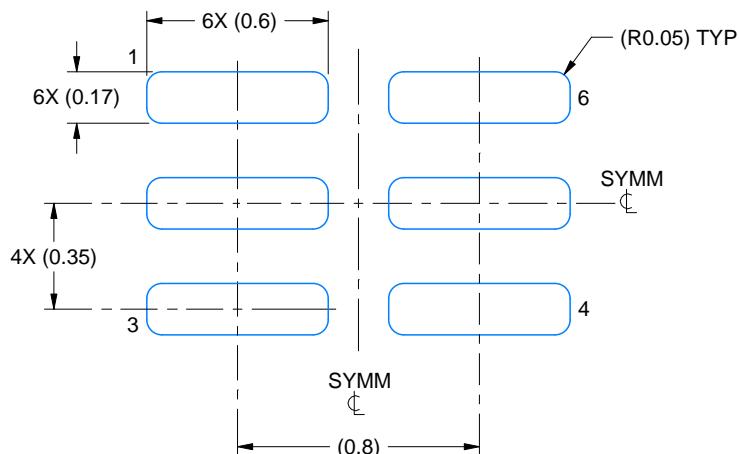
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration MO-287, variation X2AAF.

# EXAMPLE BOARD LAYOUT

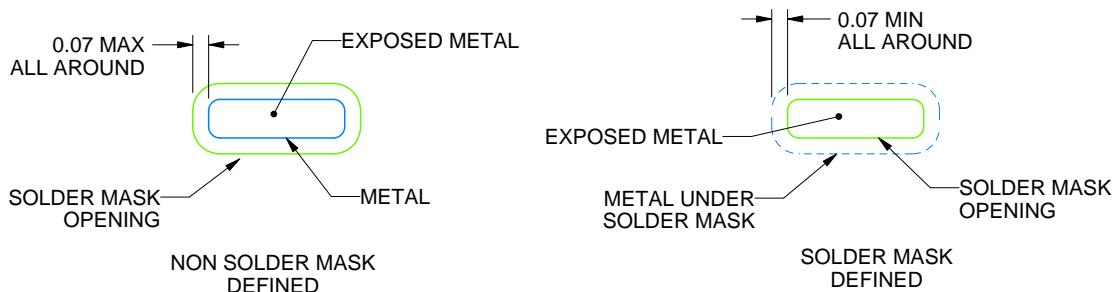
DSF0006A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:40X



SOLDER MASK DETAILS

4220597/B 06/2022

NOTES: (continued)

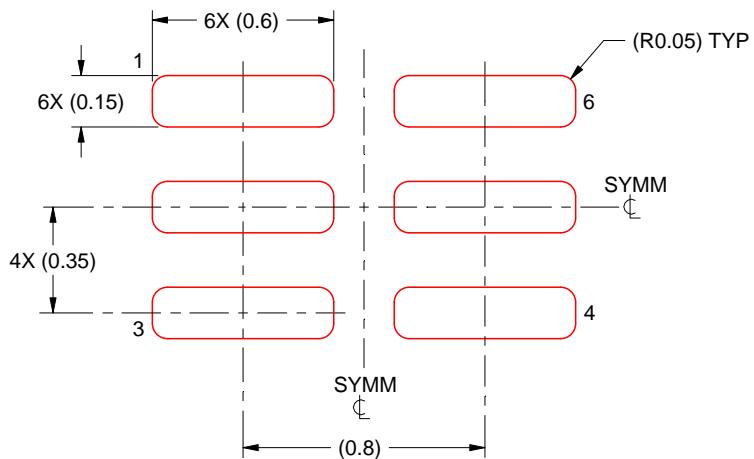
4. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).

# EXAMPLE STENCIL DESIGN

DSF0006A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.09 mm THICK STENCIL

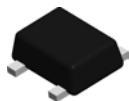
PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
SCALE:40X

4220597/B 06/2022

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

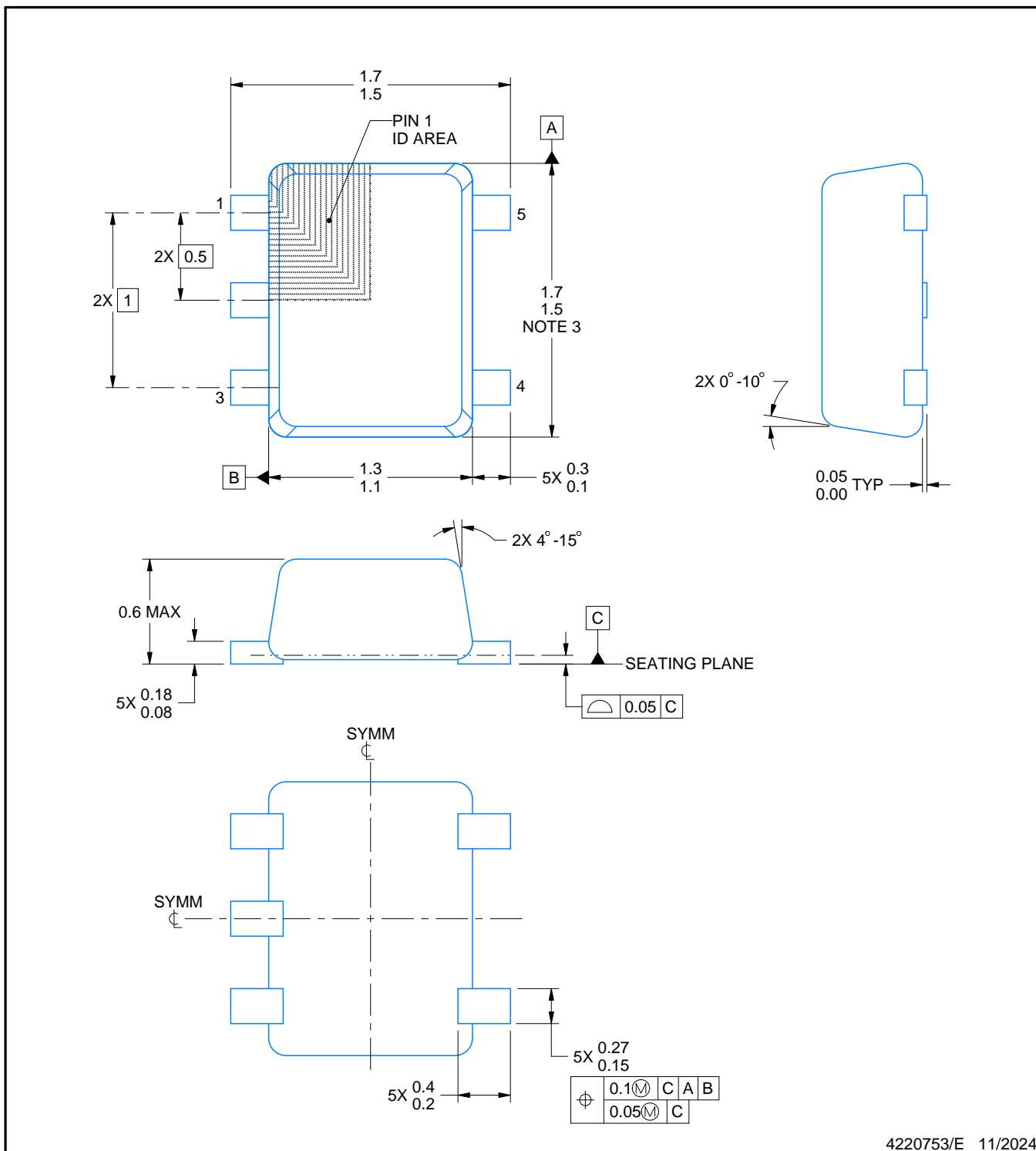
# PACKAGE OUTLINE

DRL0005A



SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



4220753/E 11/2024

## NOTES:

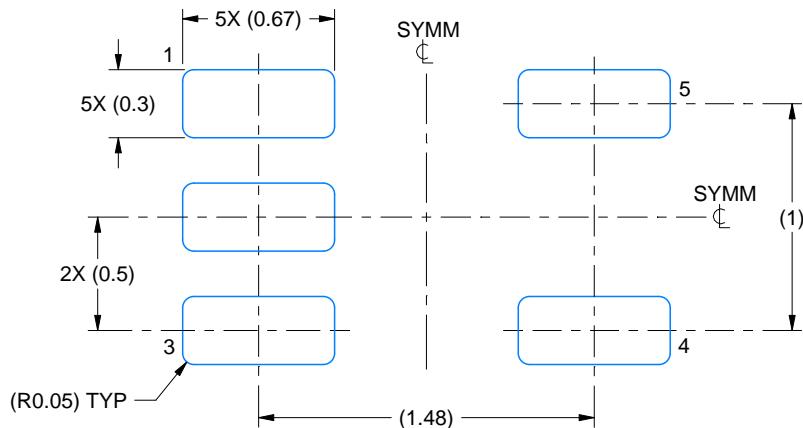
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-293 Variation UAAD-1

# EXAMPLE BOARD LAYOUT

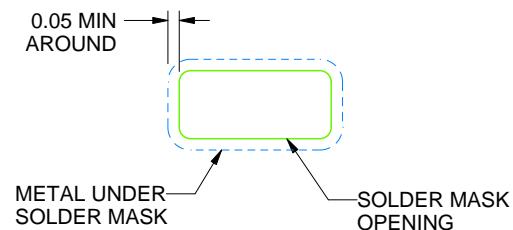
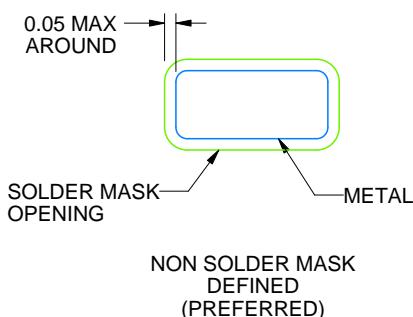
DRL0005A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



LAND PATTERN EXAMPLE  
SCALE:30X



SOLDERMASK DETAILS

4220753/E 11/2024

NOTES: (continued)

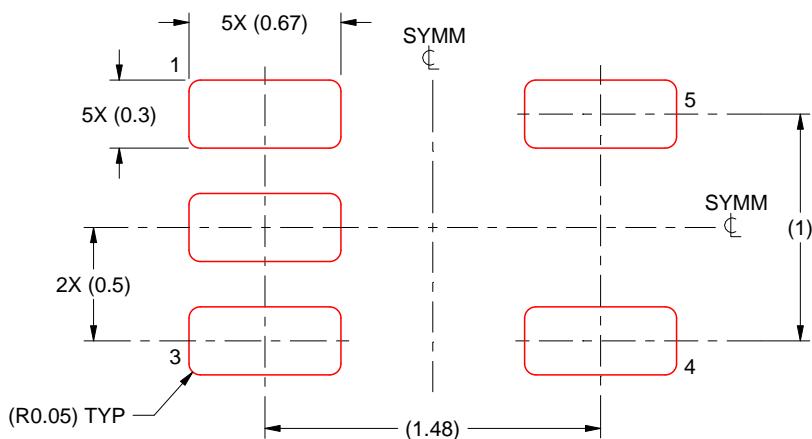
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DRL0005A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICK STENCIL  
SCALE:30X

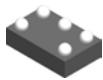
4220753/E 11/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

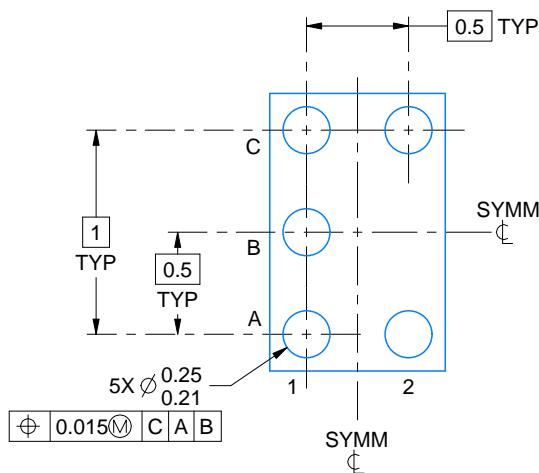
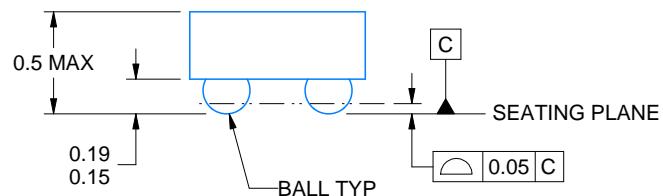
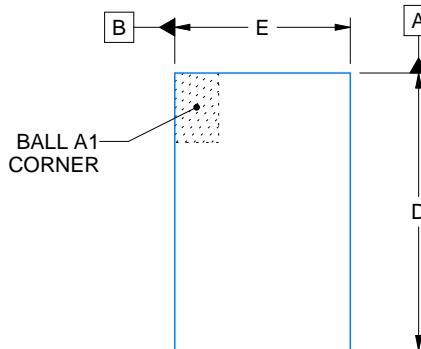
# PACKAGE OUTLINE

YZP0005



DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



4219492/A 05/2017

## NOTES:

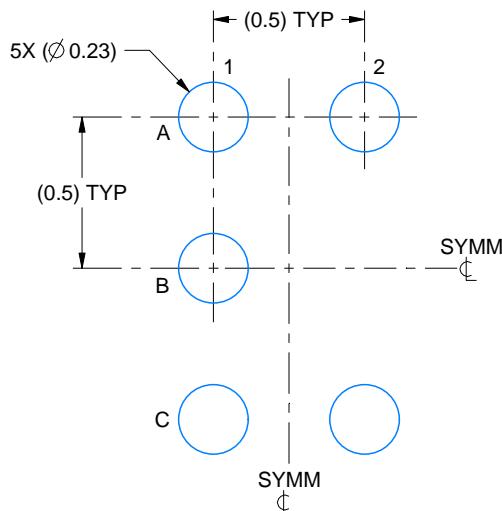
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

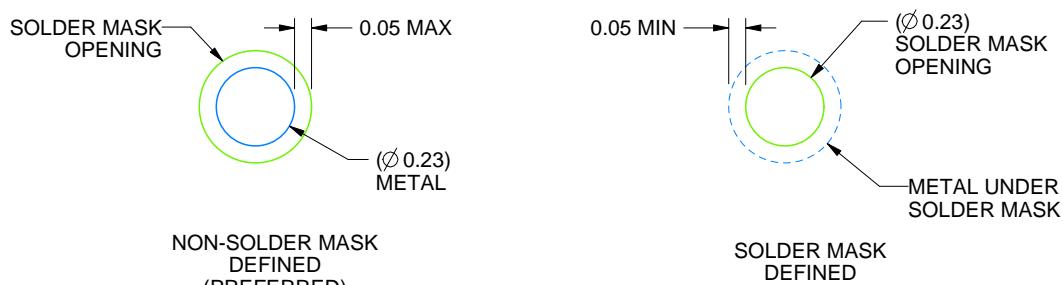
YZP0005

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE  
SCALE:40X



SOLDER MASK DETAILS  
NOT TO SCALE

4219492/A 05/2017

NOTES: (continued)

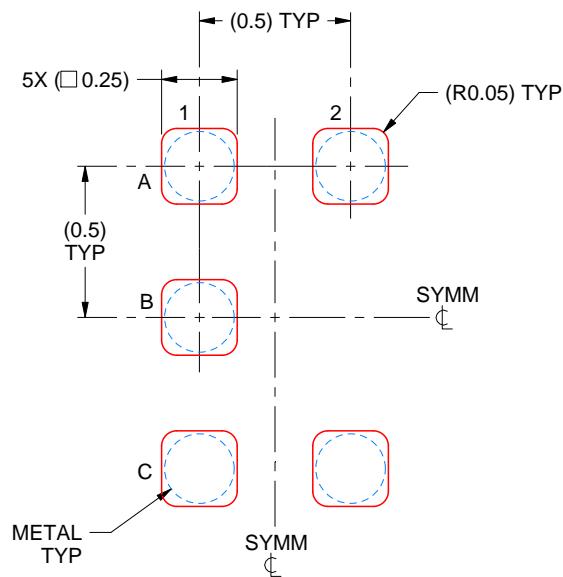
3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SNVA009 ([www.ti.com/lit/snva009](http://www.ti.com/lit/snva009)).

# EXAMPLE STENCIL DESIGN

YZP0005

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICK STENCIL  
SCALE:40X

4219492/A 05/2017

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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